

CALICE DAQv2

**Vincent Boudry,
Ch. de la Taille**

LLR, École polytechnique
LAL, Orsay

***EUDET Annual meeting
DESY, 29/09/2010***

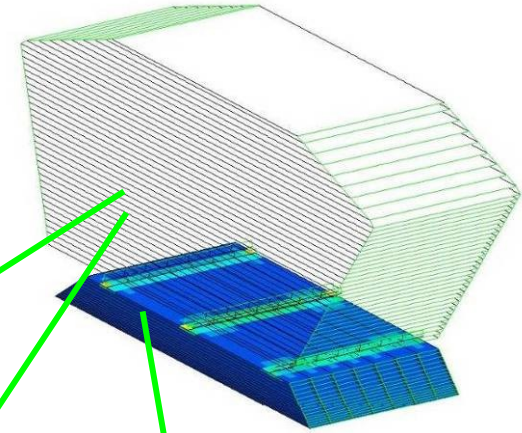




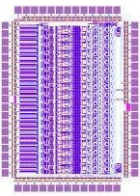
Second generation ASICs

Omega

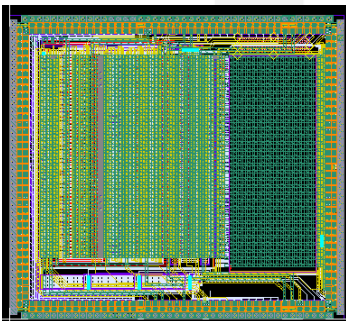
- Add auto-trigger, analog storage, digitization and token-ring readout !!!
- Include power pulsing : $< 1\%$ duty cycle
- Address integration issues asap
- Optimize commonalities within CALICE (readout, DAQ...)



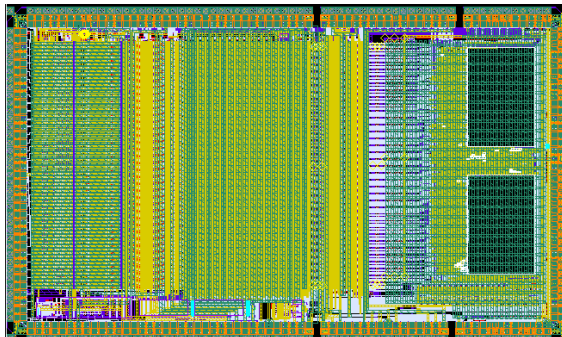
**FLC_PHY3
(2003)**



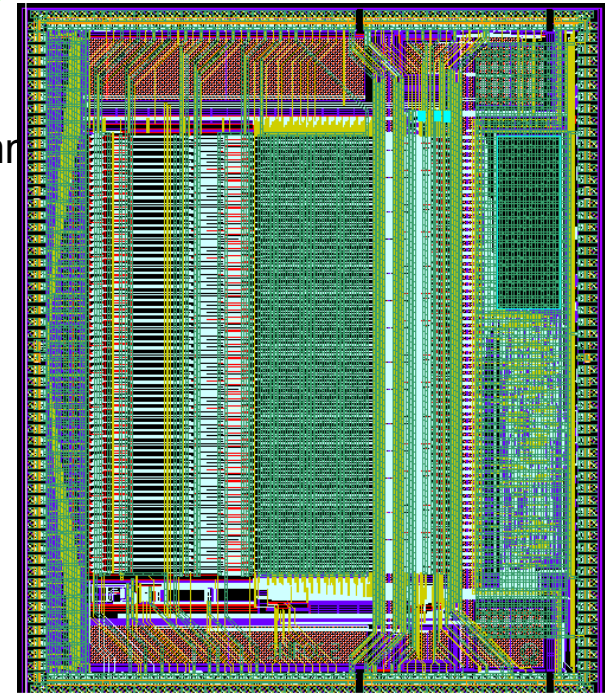
HARDROC2
SDHCAL RPC
64 ch 16 mm²



SPIROC2
AHCAL SiPM
36 ch 30 mm²

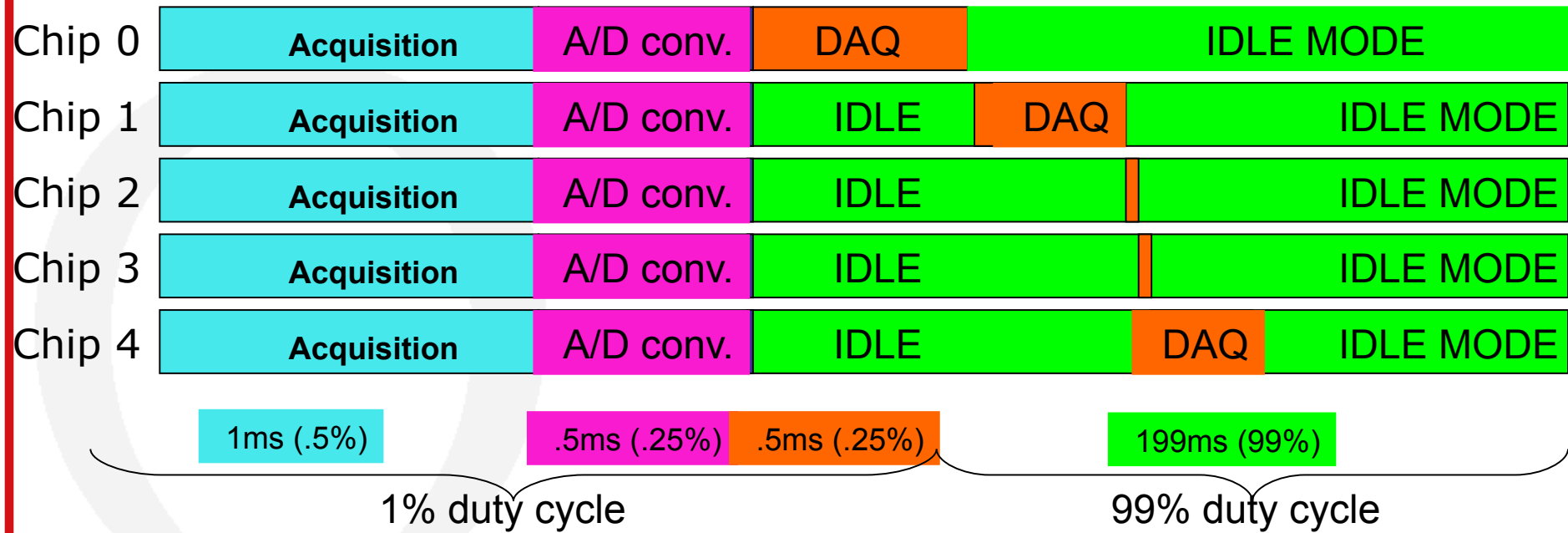
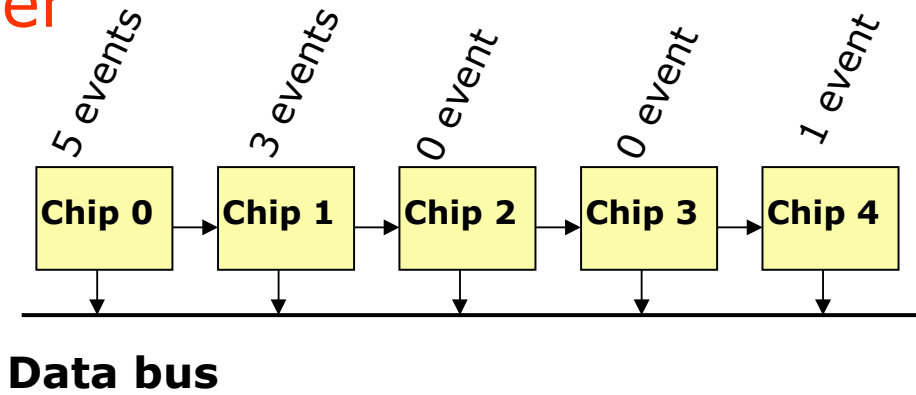
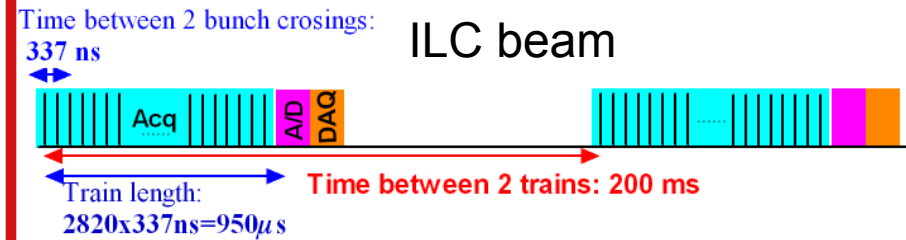


SKIROC2
ECAL Si
64 ch 70 mm²



Read out: token ring

- Readout architecture common to all calorimeters
- Minimize data lines & power



ECAL DAQ : data volume and rate

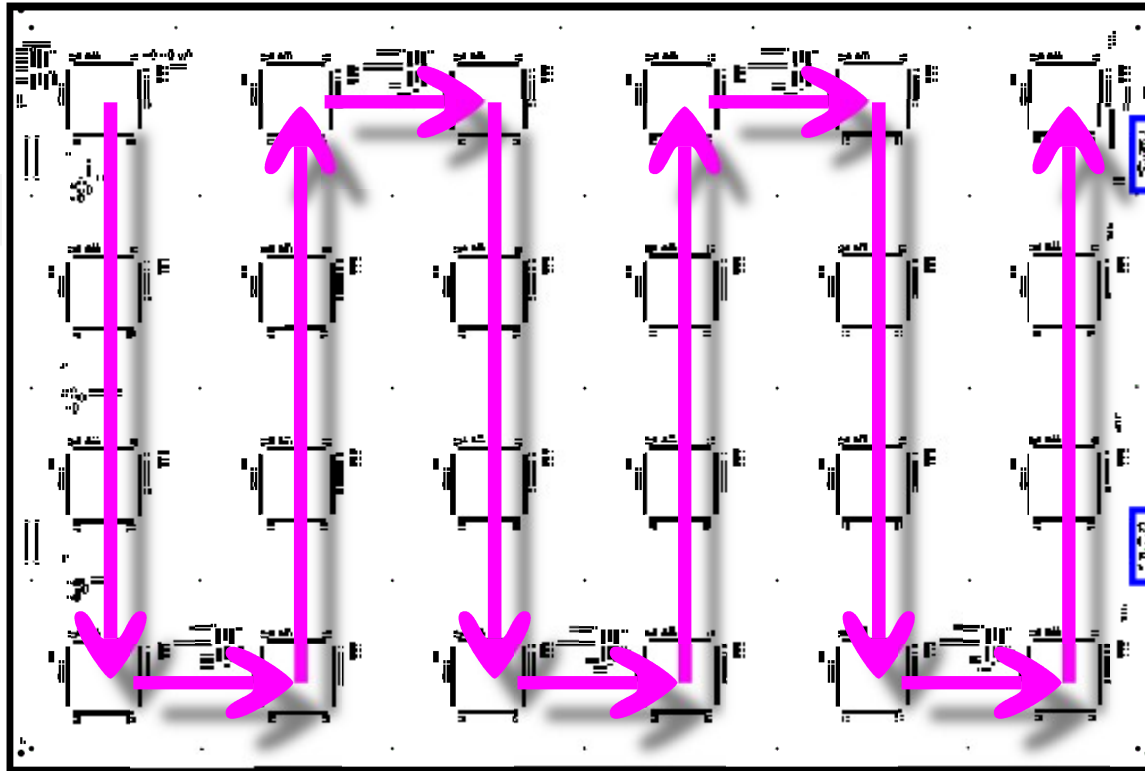
Omega

- Raw Data volume
 - 2 bytes Energy data/Channel, 20 Million channels
 - Raw data per bunch train $\sim 20\text{M} \times 5000 \times 2 \sim$
200GBytes ECAL
 - **No way to digitize inside the \sim ms train**
 - 10 kbytes/channel/train \sim 50 kbytes/ch/s
 - **Physics data rate : 90 Mbytes/train = \sim 20 bytes/ch/s**
- **Zero suppression mandatory**
 - 10^3 rate reduction -> drastic for power dissipation
 - Digitize only signals over 1/2MIP with noise $<$ MIP/10
 - Allow storage in front-end ASIC

The ASU board: clock lines

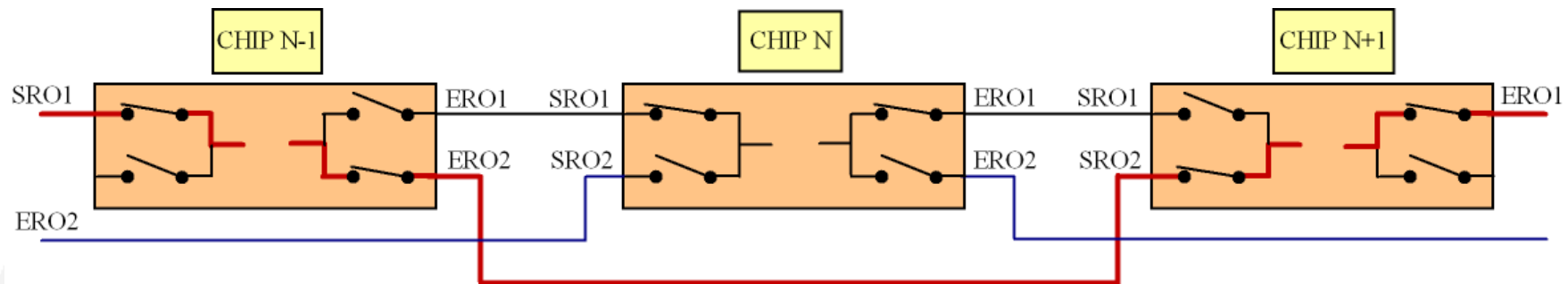
Omega

- Clocks : 2 lines, drive every other chip, terminated at the end,
- 100 ohm resistance in series inside the chip
- Clock switched off inside the chip when not used



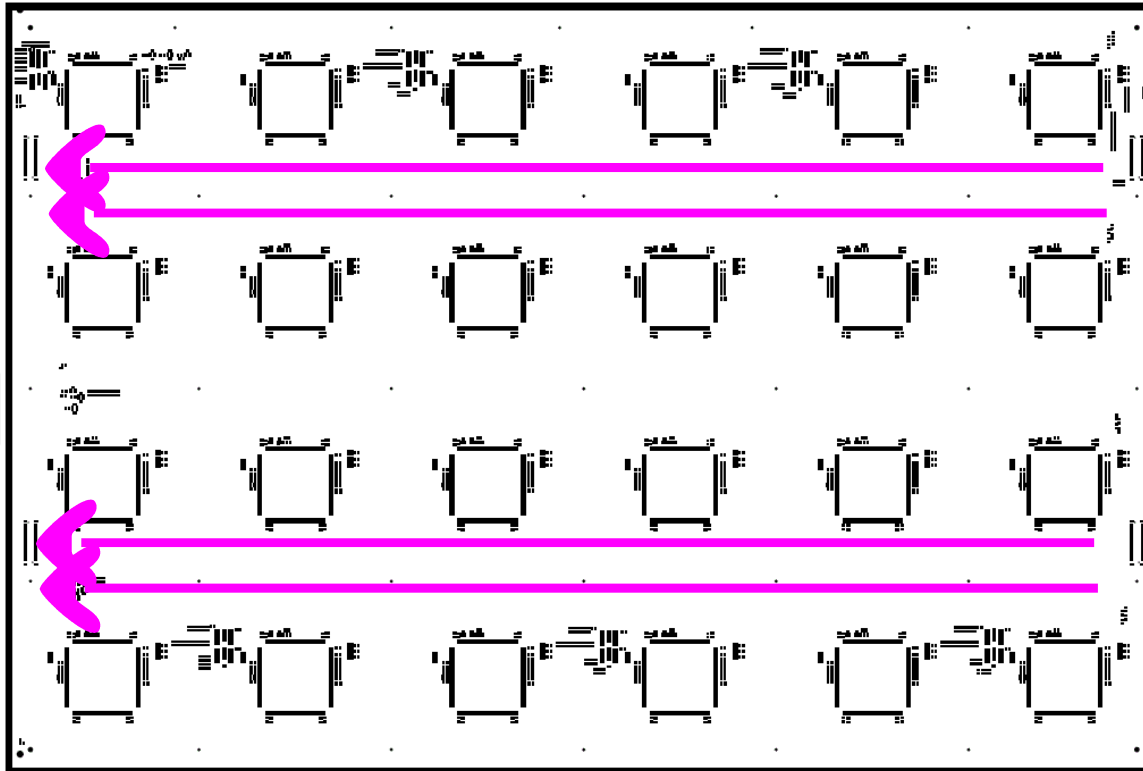
Readout protocol : token ring

- Bypass one dead chip : 2 inputs selected by slow control



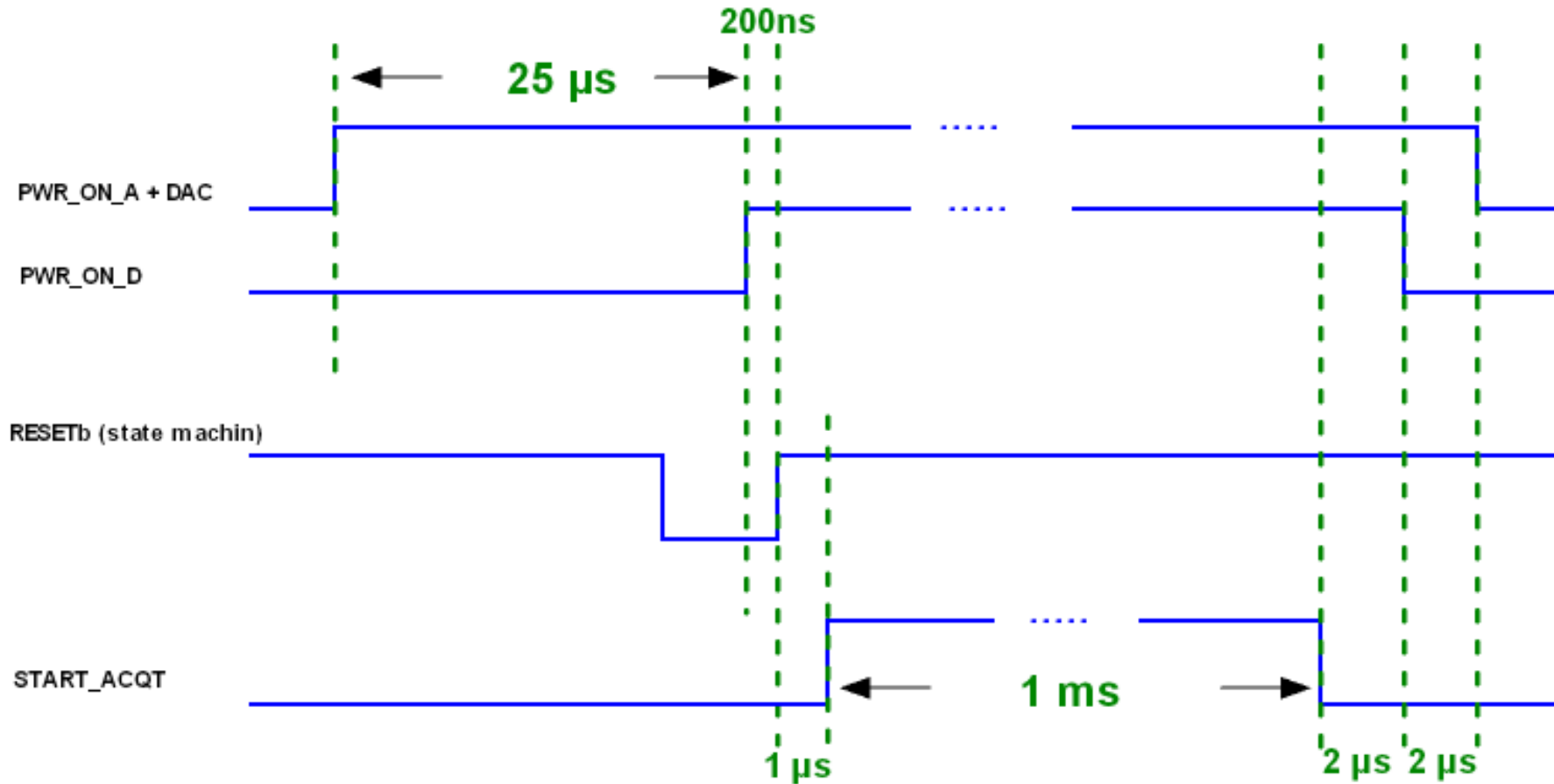
The ASU board: data lines

- Data : 4 lines : 2, doubled for redundancy
- Each chip has 2 data outputs that can be removed from each line by slow control



Power pulsing sequence

- 4 Power pulsing lines : analog, conversion, dac, digital
- Each chip can be forced on/off by slow control

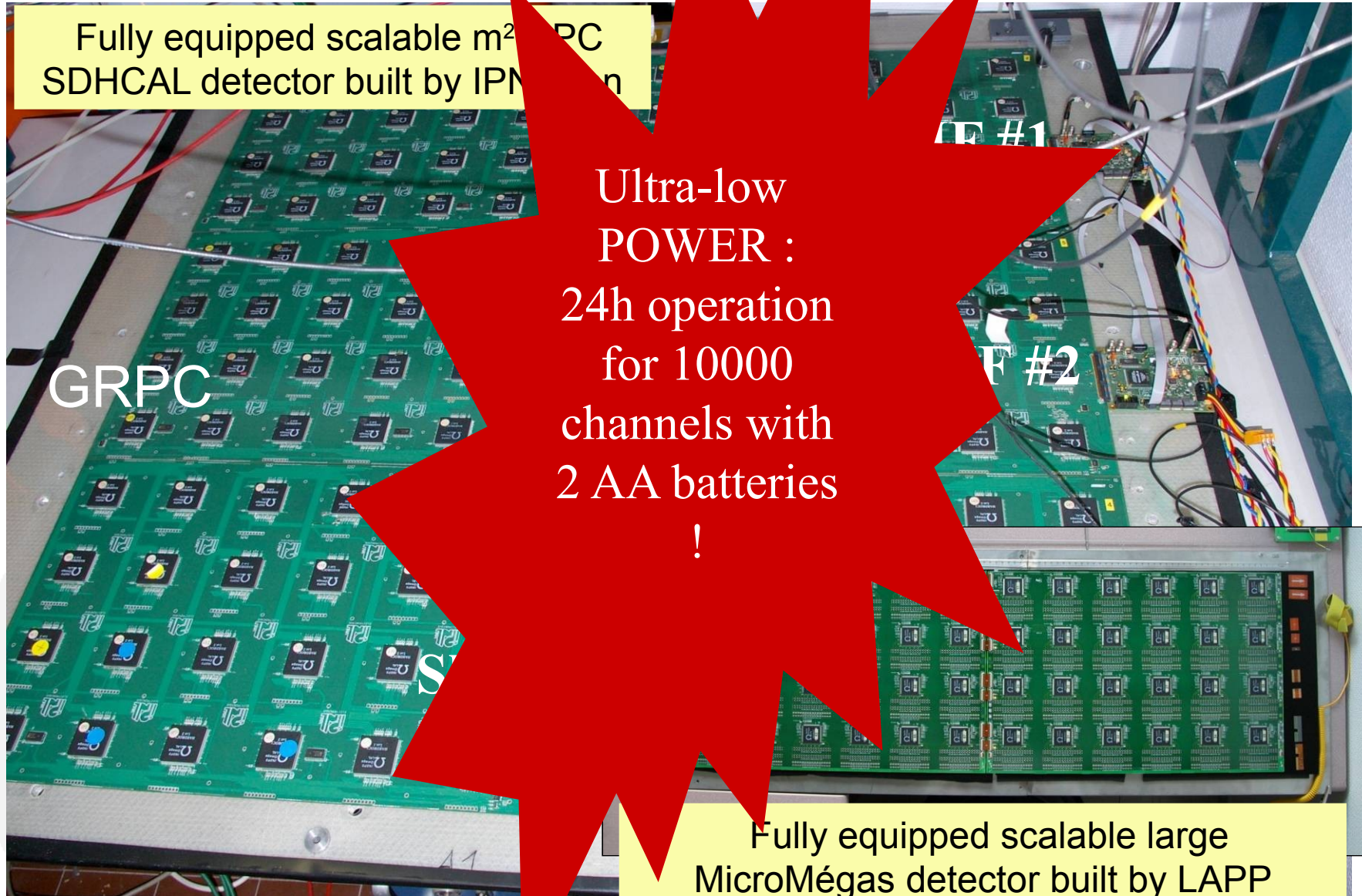


Fully equipped scalable m² RPC
SDHCAL detector built by IPN

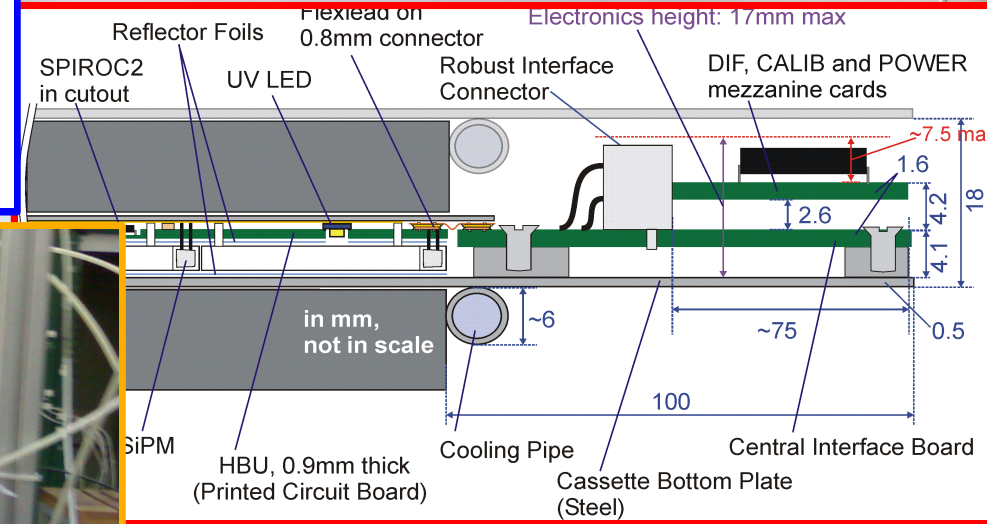
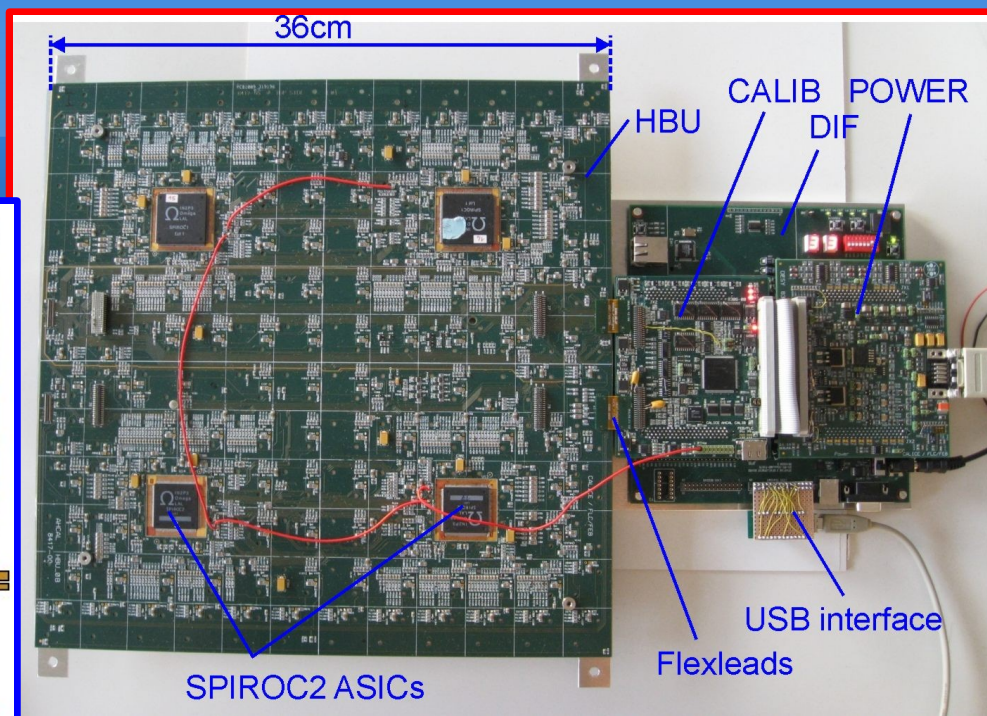
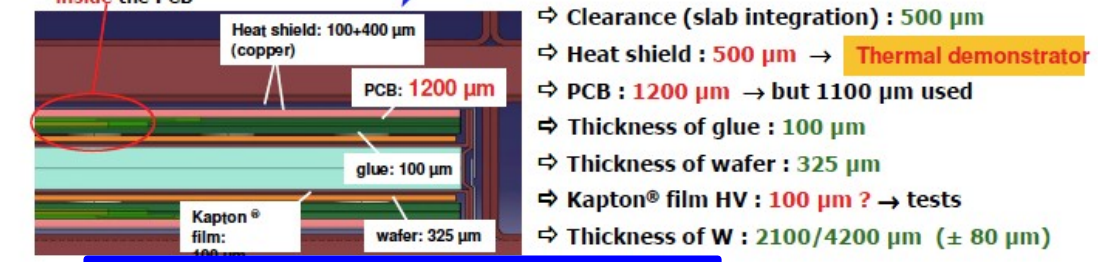
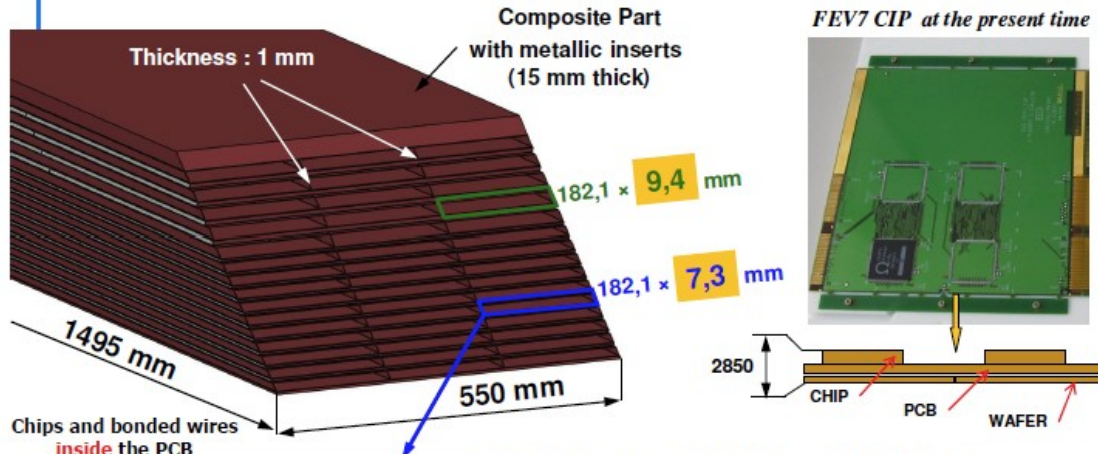
GRPC

Ultra-low
POWER :
24h operation
for 10000
channels with
2 AA batteries

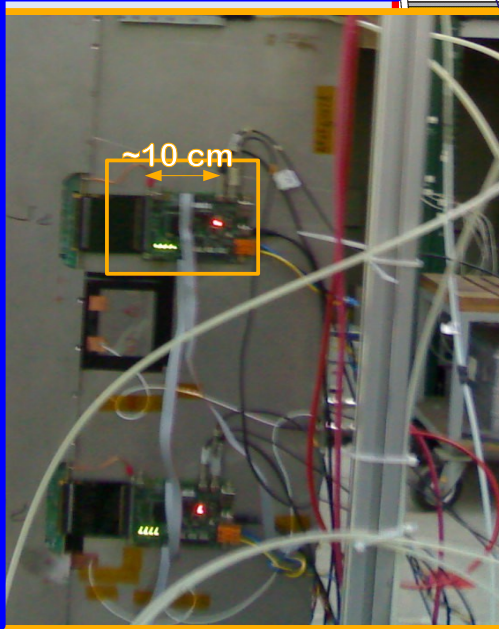
Fully equipped scalable large
MicroMégas detector built by LAPP
Annecy



Detector interfaces



ECAL

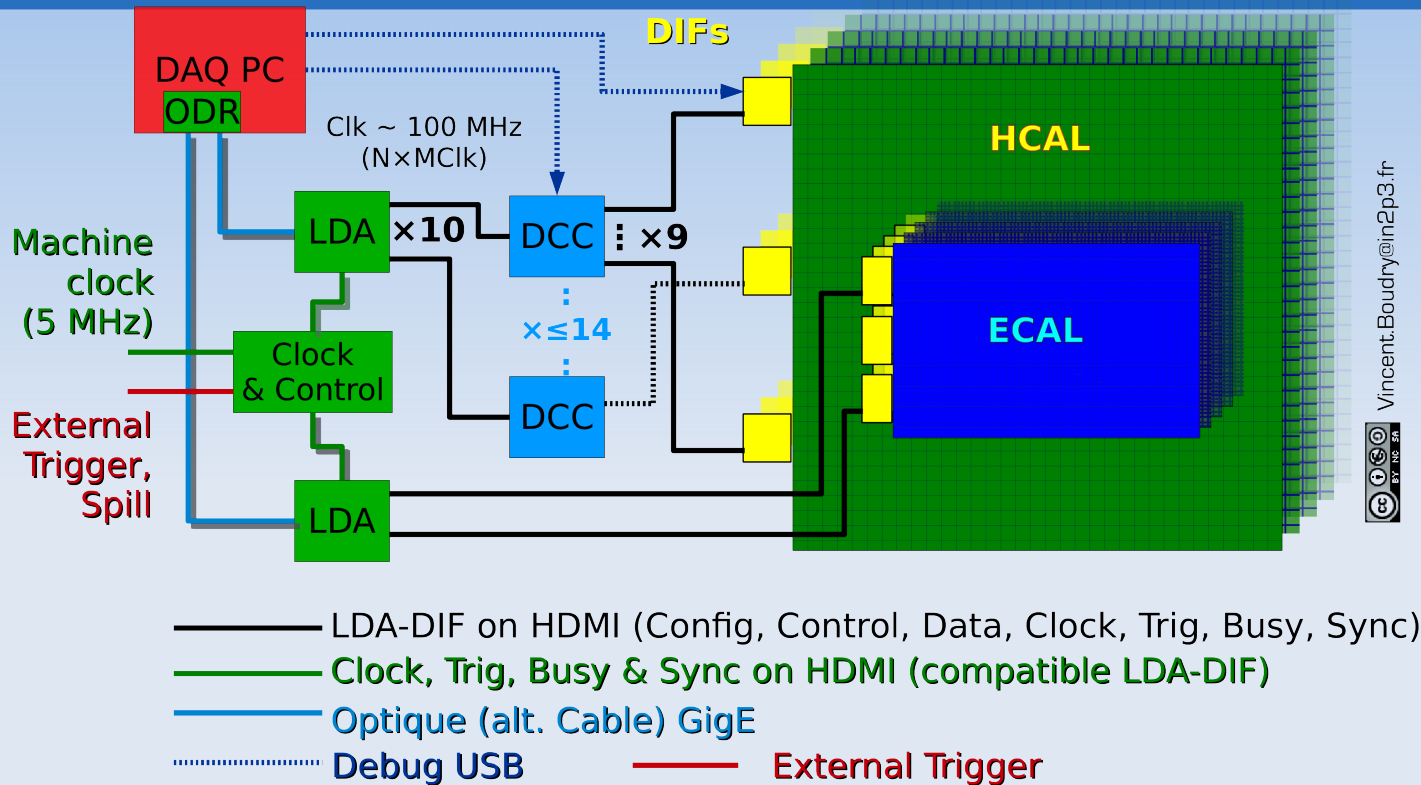


AHCAL

SDHCAL

CALICE DAQ2 scheme

Big effort for CALICE!!
 ~15 individuals from:
 • UK: CAM, MAN, UCL
 • FR: LLR, LAPP, IPNL
 • DE: DESY

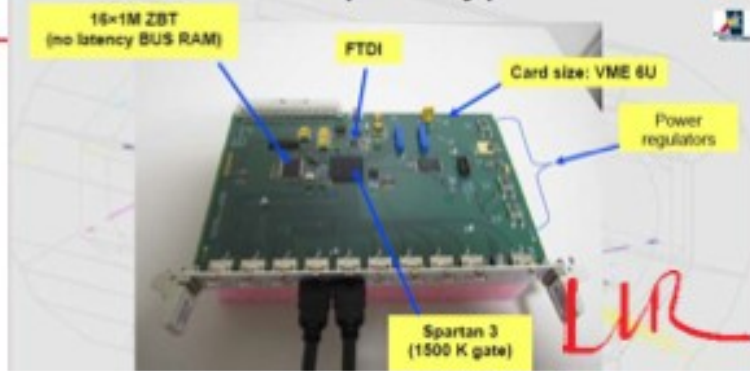


Vincent.Boudry@in2p3.fr

Most of Code, Manual and HW description is available on CALICE twiki: https://twiki.cern.ch/twiki/bin/view/CALICE/CALICE_DAQ

- Provide the digital readout of CALICE embedded front end
 - All calorimeter seen through 1 Detector Interface board (DIF)
 - 1 (opt. 2) Concentrator cards level
 - 1 Clock and Control Card (CCC) for the fast signal distribution and collection
 - HDMI cables (aka 5 twisted shielded pairs) for physical transmission; add-hoc comm. Protocol
- 3 prototypes en route: SDHCAL (120 DIFs, 400.000 digital ch), ECAL (30 DIFs, 22.000 anal. ch), AHCAL (40 DIFs, 52.000 Anal. (En. & time) ch)

DCC prototype



LDA

- The LDA (from Enterpoint) consists of :
 - Mulldonoch2 baseboard;
 - add-on HDMI board to connect to 10 DIFs;
 - an add-on ethernet board to connect to an ODR.
- Firmware development :
 - DIF \Leftrightarrow LDA link running;
 - new code soon to be posted to svn;
 - same format as ODR in svn repository.



DCC and LDA are essentially similar to an ethernet switch but using a low level protocol

They both fan-out/in fast isochronous signals on a dedicated path and commands on the 8b/10b serial link

LDA has a fast link : Gb ethernet to the upper level = ODR, and can connect to 10 DIFs or DCC with the 8b/10b serial link

DCC can connect to 1 LDA and 9 DIFs using the 8b/10b serial link, data from DIF are buffered and sent to the LDA

CCC

- Overall status unchanged for a while.
- Fans out clocks, fast commands and control signals.
- Fans in busy.
- Full complement of 10 boards with power supplies tested.
- One in LLR and one in LAPP.
- CCC link to LDA still needs to be done :
 - Board designed and firmware developed for testing;
 - Soon to produce enough boards for all LDAs.



ODR

- Receive data on 4x fibre (RX),
- Write to disk FAST (>150MB)
- Send data up fibre (TX)
- Controlled from Linux driver
- DOOCs Interface

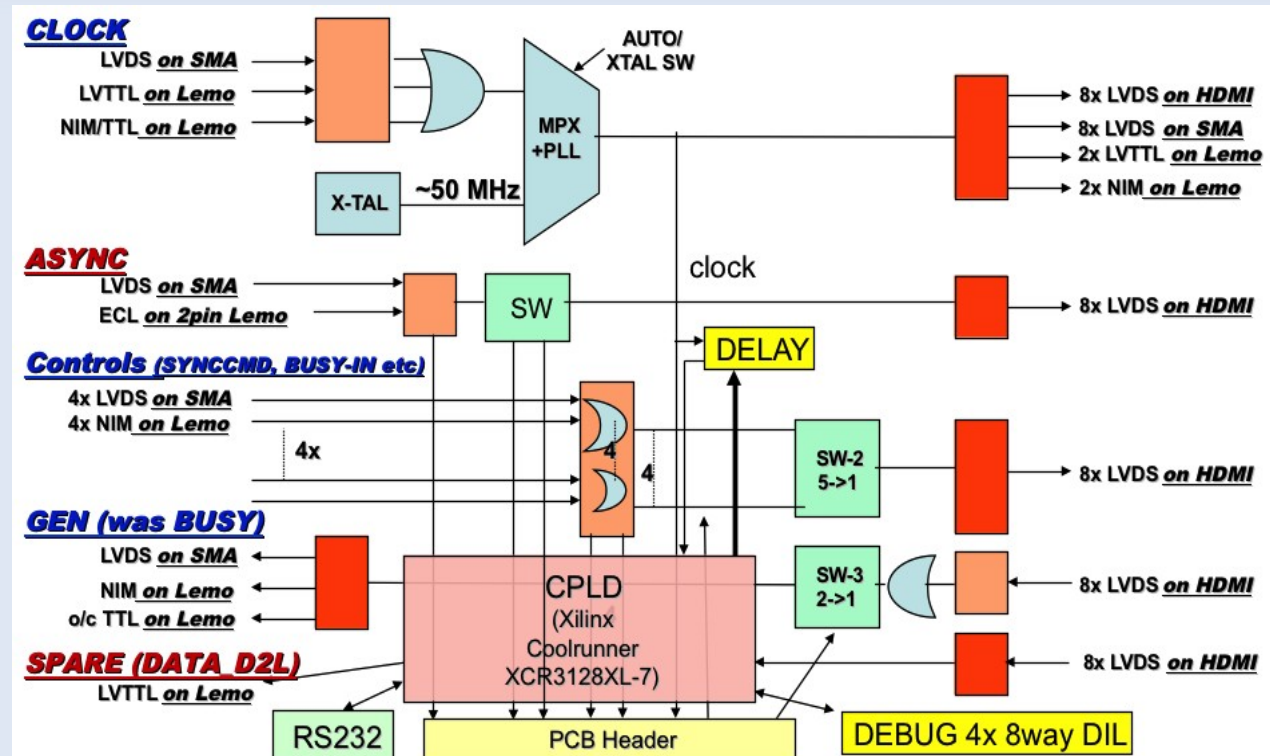
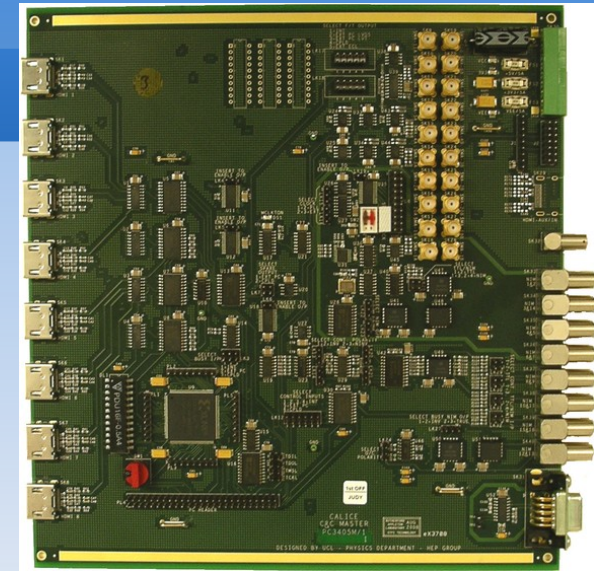


Documentation / repository

- All components *should* have extensive documentation on twiki : it is being updated and as components are basically done, can soon be finalised.
- Twiki main :
 - <https://twiki.cern.ch/twiki/bin/view/CALICE/CALICEDAQ>
- Also list of hardware availability /status started.
 - <https://twiki.cern.ch/twiki/bin/view/CALICE/HardwareList>

Clock and Control Card

- Developed in UCL (M. Warren, M. Postranecky)
- Distributes on 8 channels (HDMI, SMAs, NIM, ...) via dedicated circuiterie
 - Int | ext clock
 - Fast Signal (Trigger | Sync)
- Sums-up BUSY
- Performs Trigger logics
 - CPLD
- Was used as DIF-Master (dev^t of LAPP)
 - Aka also sending hard-coded commands to DIF directly



Beam InterFace card

Basis:

- CALICE chips use auto-trigger
 - ▶ Readout can be triggered by single event using external trigger (e.g. beam hodoscope)
 - “Single event” mode
 - History of Chip is usable (e.g. in case of selective ext. trigger)
 - ▶ Readout triggered by environmental internal or external trigger
 - ◆ Chip full
 - ◆ ILC-like mode (end-of-spill)
- Require some device to readout the beam line parameters
 - ▶ Scintillators; Cherenkov PM (coding of CEDAR bits)
 - ▶ Time of event (⇒ rec for wire chambers)

Implementation

- 2 solutions
 - ▶ Add-hoc card for interfaces with a CALICE ROC (SPIROC ?) + 1 DIF
 - ▶ Small adaptation (buffers) card on a DIF + “simulation” of a digital ROC in the FPGA
- Both offer full compatibility with CALICE DIF for the DAQv2.
- To be implemented for 2nd version of CALICE beam test
- One of the tasks of AIDA (WP8.6.2)

HW status

- 10 ECAL DIF ready and working; 10 in prod; mat for 40 in total (CAM)
- DHCAL DIF: 165/170 cards tested & ready (LAPP)
- AHCAL DIF: in design, prod in NIU → 4 unit
- CCC: 10 cards ready; 4 in use in 4 labs; 3 more shipped → LLR
- DCC: 3 prototypes ready; 2 cards being tested → 20 end of october
- LDA: 20 main board OK
 - ▶ 5 v1 + 15 v2 Ethernet mezzanine : ✓
 - ▶ 6 CCC mezzanine; clock OK — Busy & Trigger not yet tested (TBC)
 - ▶ 20 HDMI Mezzanine: faulty connectors on 8 → in repair
- ODR + PC
 - ▶ 8 ODR ready ; network card being used instead for debugging
 - ▶ 6 PC available: 1 in LLR ; 3 other ready; OS needs to be upgraded
- Future BIF: to be developed (part of AIDA)

**~ No more basic problem with HW
Reliability of HDMI connectors mechanics ?**

FW status

LDA+CCC comm

Reuse MUX from DCC

	LDA	DCC	DIF's
Ethernet	✓ at full speed		
CCC	Clk; Trig; Busy	Clk; Trig; Busy	Clk; Trig; Busy
Nlinks up	9/10 conn. no MUX	9	1
Fast Commands	✓	✓	✓
Block transfert	✓	✓	✓
Data ¹⁾	✓ (< 50 MHz)	✓ (< 50 MHz)	✓ (<50 MHz)
ROC			Structure ✓ Adapt SDHCAL USB Code on going...

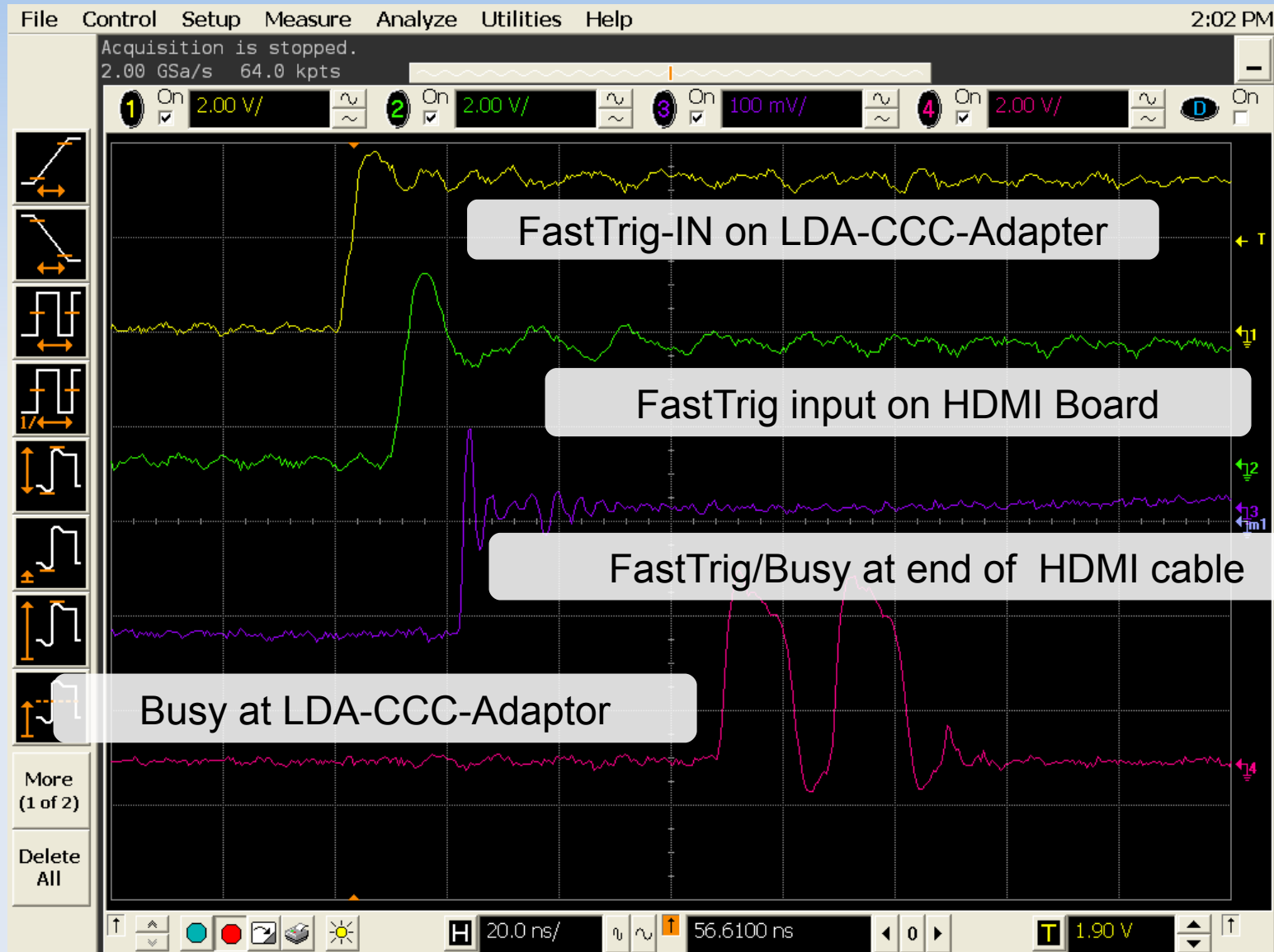
- FW have been advancing rather fast during the last 3 months

Generic code for all DIFs

Many progresses recently

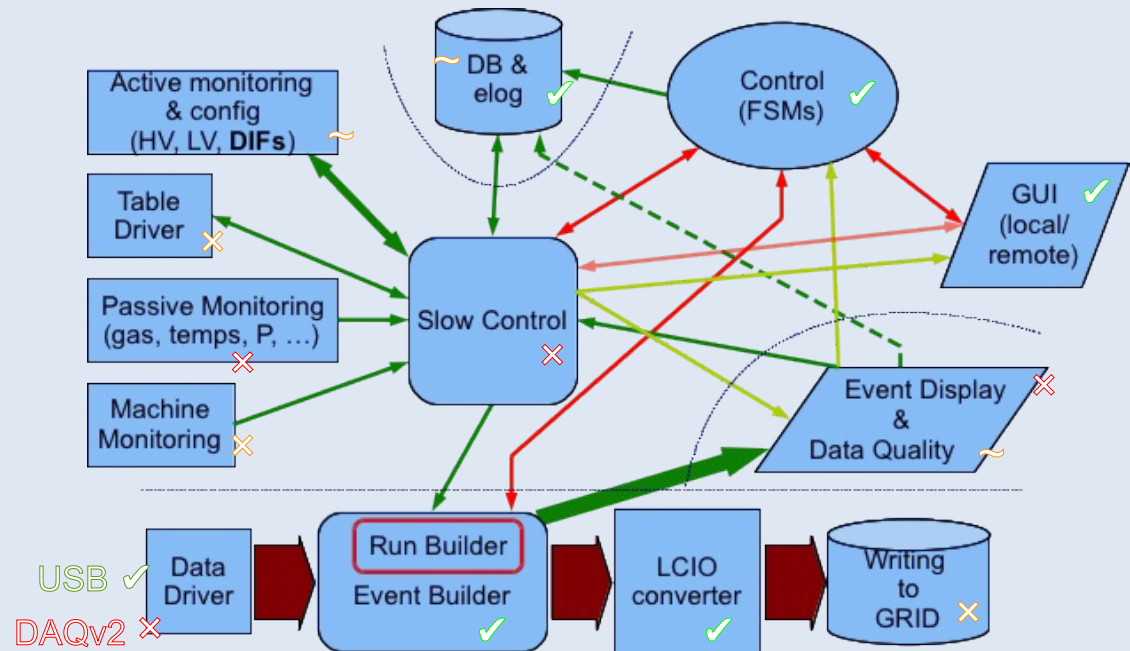
End of October for first full minimal usable chain ?

CCC↔LDA Fast signals tests (from 29/09/2010 15:45!)



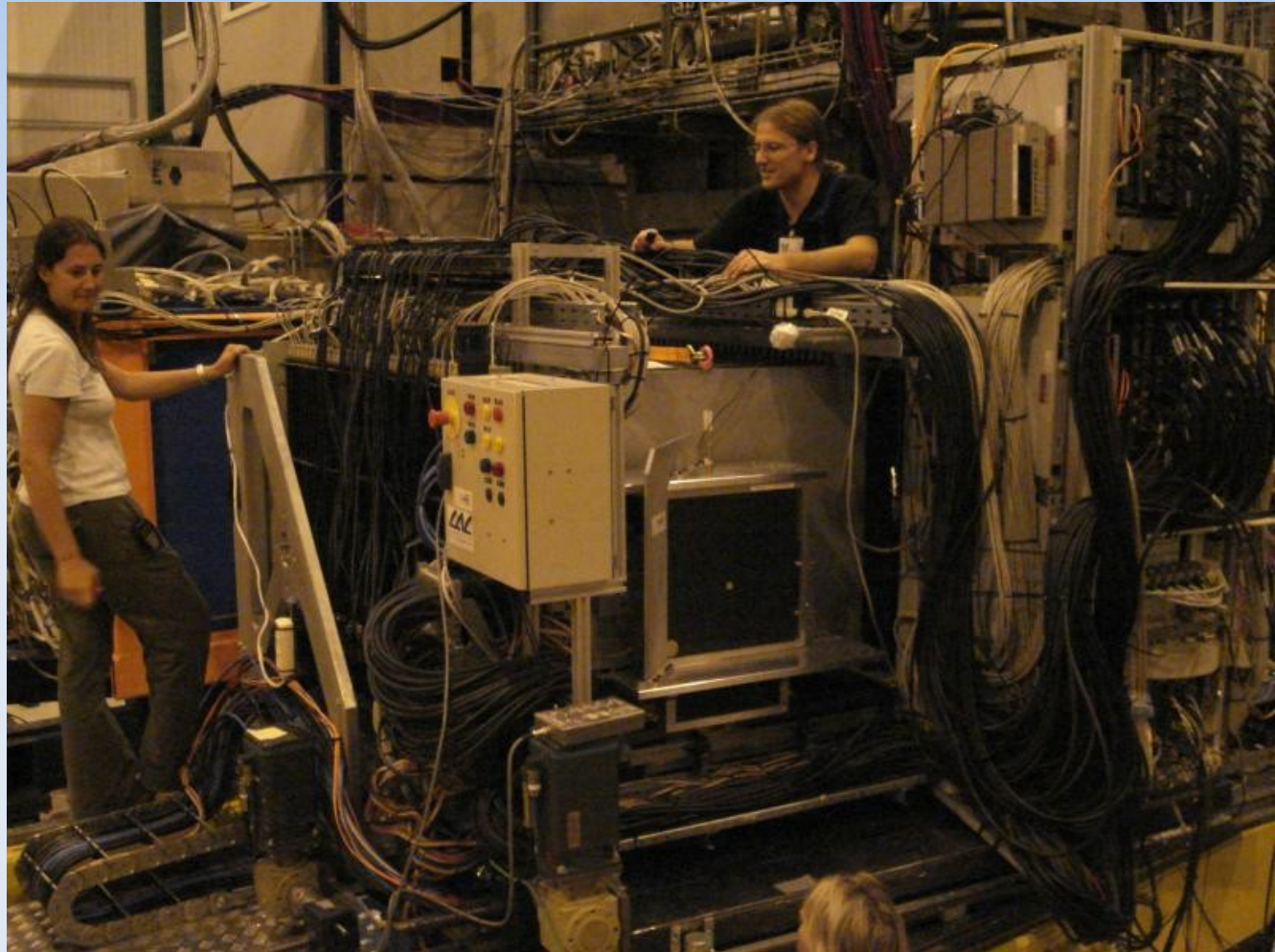
SW status

- Many progress
 - ▶ XDAQ (L. Mirabito, Ch. Combaret) “critical part” complete:
 - ◆ Writing of LCIO data in RAW format
 - ◆ versatile online analysis framework (root histos)
 - ▶ DAQ2 interface ↔ XDAQ being worked on (D. Decotigny, G. Vouters)
- Missing utilities
 - ▶ Semi-automatic noisy channels spotting & correcting (monitoring) ←←←
 - ▶ Clean Slow control
 - ▶ interface to CondDB;
 - ▶ event display (most prob^{ly} DRUID)
 - ▶ interface to the GRID
 - ▶ interface to the machine
- Analysis environment (IPNL)
 - ▶ rec. data format in LCIO



Installation

- mechanics
 - ▶ mod. VME crate for
 - ◆ DCC
 - ◆ CCC
 - ▶ Special box for LDA
 - ▶ Support for cables
- Final set-up not yet known:
 - ▶ stand alone SDHCAL
 - ▶ stand alone ECAL
 - ▶ Stand alone AHCAL
 - ▶ Combined test
- → 5 m long HDMI cables
 - ▶ halogen free;



Conclusions

- Technological prototypes of CALICE are getting close (1st will be SDHCAL → Spring 2011)
 - ▶ 2nd version of ROC chips available
 - ▶ Being integrated in large prototypes → extensive TB in 2011
- All DAQ HW elements available
 - ▶ FW almost ready
 - ▶ Accomplishment of a long process
- SW: XDAQ survived natural selection
- Combined (with other system) ≥ 2012
 - ▶ Prepare HW and SW beforehand
 - ◆ SW & HW ↔ TLU & EUDAQ first